1.

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Autore	Svensson Isak
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Livello bibliografico	Monografia
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Nota di contenuto	Front Cover ; Author biography; Other titles in UQP's New Approaches to Peace and Conflict series; Title page; Imprint page; Dedication; Note from Series Editor; Contents; List of tables and graphs; Preface; Introduction; Chapter 1 - Where and when do religious conflicts occur?; Chapter 2 - Which religious conflicts are difficult to resolve?; Chapter 3 - How do religious issue conflicts get resolved through peace agreements?; Chapter 4 - How do religious issue conflicts get resolved through concessions?; Chapter 5 - Towards a theory of desacralisation; Chapter 6 - Implications AcknowledgementsNotes; References; Index
Sommario/riassunto	<P style=""MARGIN: 0in 0in 0pt"" class=MsoNormal>An exploration of how religious dimensions affect the possibilities for conflict resolution in civil war, this account systematically attempts to map out the religious dimensions of internal armed conflicts and to explain the conditions under which religious dimensions impede peaceful settlement. Drawing upon empirical work on global data, and based on the Uppsala Conflict Data Program, this book shows how religious identities and incompatibilities influence the likelihood of agreements

	and the mechanisms through which parties and third-party me

2.	Record Nr.	UNINA9910829907903321
	Autore	Duan Baoyan
	Titolo	Electromechanical coupling theory, methodology and applications for high-performance microwave equipment / / Baoyan Duan and Shuxin Zhang
	Pubbl/distr/stampa	Hoboken, New Jersey : , : John Wiley & Sons, , [2023] ©2023
	ISBN	1-119-90442-0 1-119-90440-4
	Descrizione fisica	1 online resource (339 pages)
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	Nota di contenuto	Cover -- Title Page -- Copyright -- Contents -- About the Authors -- Preface -- Chapter 1 Background of Electromechanical Coupling of Electronic Equipment -- 1.1 Introduction -- 1.2 Characteristics of Electronic Equipment -- 1.3 Components of Electronic Equipment -- 1.3.1 Mechanical and Structural Part of Electronic Equipment -- 1.3.2 Electrical Part of Electronic Equipment -- 1.4 On research of Electromechanical Coupling (EMC) of Electronic Equipment -- 1.4.1 Current Status of Research on Electromechanical Coupling of Electronic Equipment -- 1.4.2 The Development Trends of Electronic Equipment -- 1.4.2.1 High Frequency and High Gain -- 1.4.2.2 Broad Bandwidth, Multiband, and High Power -- 1.4.2.3 High Density and Miniaturization -- 1.4.2.4 Fast Response and High Pointing Accuracy -- 1.4.2.5 Good Environmental Adaptability -- 1.4.2.6 Integration -- 1.4.2.7 Intelligence -- 1.5 Problem of the Traditional Design Method of Electronic Equipment -- 1.5.1 Traditional Design Method and Problems

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